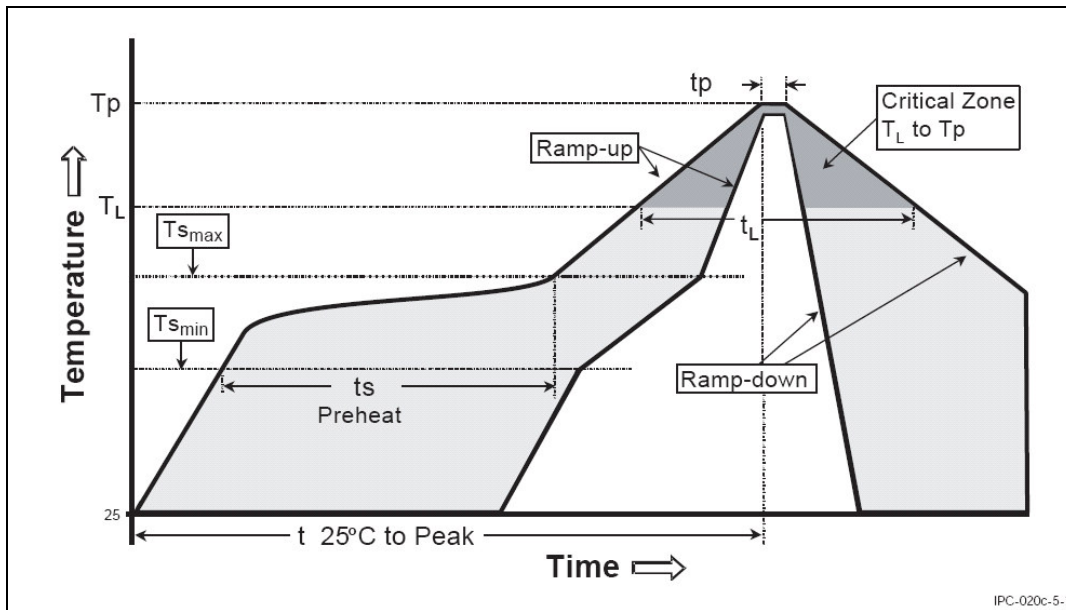


Solder profile for lead free reflow process

Figure 1 Classification Reflow Profile



refer to IPC/JEDEC J-STD-020C

Table 1 Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T_{smax} to T_p)	3°C/second max.
Preheat	
- Temperature Min (T_{smin})	150°C
- Temperature Max (T_{smax})	200°C
- Time (t_{smin} to t_{smax})	90-180 seconds
Time maintained above:	
- Temperature (T_L)	217°C
- Time (t_L)	60-150 seconds
Peak/Classification Temperature (T_p)	See Table 2
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds (WE-GF/WE-LAN: 10 s; $T_p=245^\circ\text{C}$)
Ramp-Down Rate	natural cooling
Time 25°C to Peak Temperature	8 minutes max.

Table 2 Package Classification Reflow Temperature

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 +0 °C *	260 +0 °C *	260 +0 °C *
1.6 mm - 2.5 mm	260 +0 °C *	250 +0 °C *	245 +0 °C *
≥2.5 mm	250 +0 °C *	245 +0 °C *	245 +0 °C *

refer to IPC/JEDEC J-STD-020C

Note: All temperatures refer to topside of the package, measured on the package body surface

Recommended for all parts which are marked with the RoHS logo in the data sheet



checked	approved	MST	Version 2	22.08.06
		MST	Version 1	07.07.05
		name	Modification	date